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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	360
Number of Logic Elements/Cells	2880
Total RAM Bits	40960
Number of I/O	186
Number of Gates	199000
Voltage - Supply	2.375V ~ 2.625V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 70°C (TA)
Package / Case	256-BGA
Supplier Device Package	256-FBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep1k50fc256-3

...and More Features

- -1 speed grade devices are compliant with **PCI Local Bus Specification, Revision 2.2** for 5.0-V operation
- Built-in Joint Test Action Group (JTAG) boundary-scan test (BST) circuitry compliant with IEEE Std. 1149.1-1990, available without consuming additional device logic.
- Operate with a 2.5-V internal supply voltage
- In-circuit reconfigurability (ICR) via external configuration devices, intelligent controller, or JTAG port
- ClockLock™ and ClockBoost™ options for reduced clock delay, clock skew, and clock multiplication
- Built-in, low-skew clock distribution trees
- 100% functional testing of all devices; test vectors or scan chains are not required
- Pull-up on I/O pins before and during configuration
- Flexible interconnect
 - FastTrack® Interconnect continuous routing structure for fast, predictable interconnect delays
 - Dedicated carry chain that implements arithmetic functions such as fast adders, counters, and comparators (automatically used by software tools and megafunctions)
 - Dedicated cascade chain that implements high-speed, high-fan-in logic functions (automatically used by software tools and megafunctions)
 - Tri-state emulation that implements internal tri-state buses
 - Up to six global clock signals and four global clear signals
- Powerful I/O pins
 - Individual tri-state output enable control for each pin
 - Open-drain option on each I/O pin
 - Programmable output slew-rate control to reduce switching noise
 - Clamp to V_{CCIO} user-selectable on a pin-by-pin basis
 - Supports hot-socketing

- Software design support and automatic place-and-route provided by Altera development systems for Windows-based PCs and Sun SPARCstation, and HP 9000 Series 700/800 workstations
- Flexible package options are available in 100 to 484 pins, including the innovative FineLine BGA™ packages (see [Tables 2 and 3](#))
- Additional design entry and simulation support provided by EDIF 2 0 0 and 3 0 0 netlist files, library of parameterized modules (LPM), DesignWare components, Verilog HDL, VHDL, and other interfaces to popular EDA tools from manufacturers such as Cadence, Exemplar Logic, Mentor Graphics, OrCAD, Synopsys, Synplcity, VeriBest, and Viewlogic

Table 2. ACEX 1K Package Options & I/O Pin Count *Notes (1), (2)*

Device	100-Pin TQFP	144-Pin TQFP	208-Pin PQFP	256-Pin FineLine BGA	484-Pin FineLine BGA
EP1K10	66	92	120	136	136 (3)
EP1K30		102	147	171	171 (3)
EP1K50		102	147	186	249
EP1K100			147	186	333

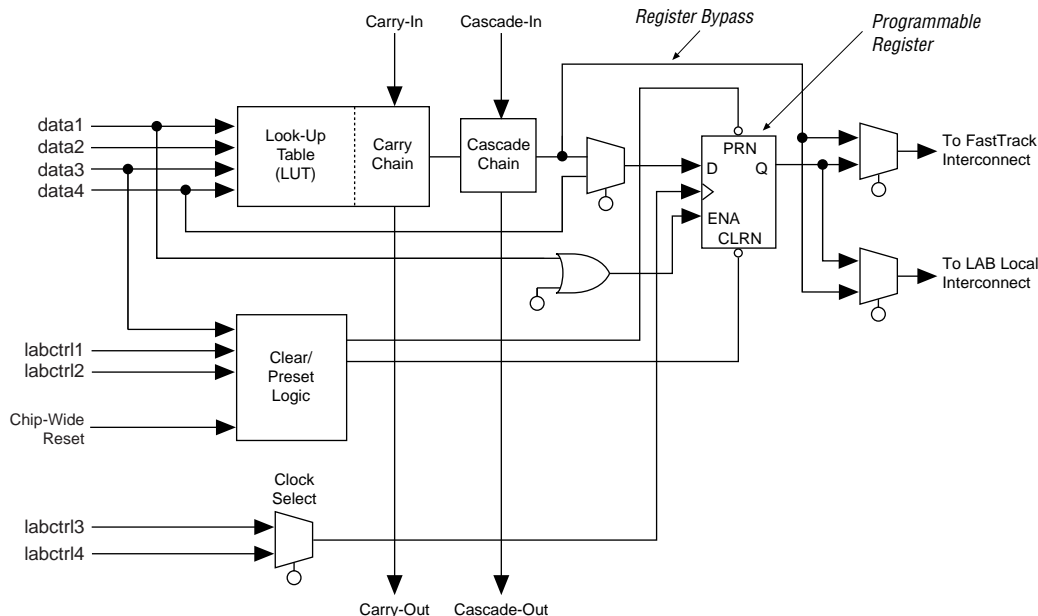
Notes:

- (1) ACEX 1K device package types include thin quad flat pack (TQFP), plastic quad flat pack (PQFP), and FineLine BGA packages.
- (2) Devices in the same package are pin-compatible, although some devices have more I/O pins than others. When planning device migration, use the I/O pins that are common to all devices.
- (3) This option is supported with a 256-pin FineLine BGA package. By using SameFrame™ pin migration, all FineLine BGA packages are pin-compatible. For example, a board can be designed to support 256-pin and 484-pin FineLine BGA packages.

Table 3. ACEX 1K Package Sizes

Device	100-Pin TQFP	144-Pin TQFP	208-Pin PQFP	256-Pin FineLine BGA	484-Pin FineLine BGA
Pitch (mm)	0.50	0.50	0.50	1.0	1.0
Area (mm ²)	256	484	936	289	529
Length × width (mm × mm)	16 × 16	22 × 22	30.6 × 30.6	17 × 17	23 × 23

Figure 8. ACEX 1K Logic Element



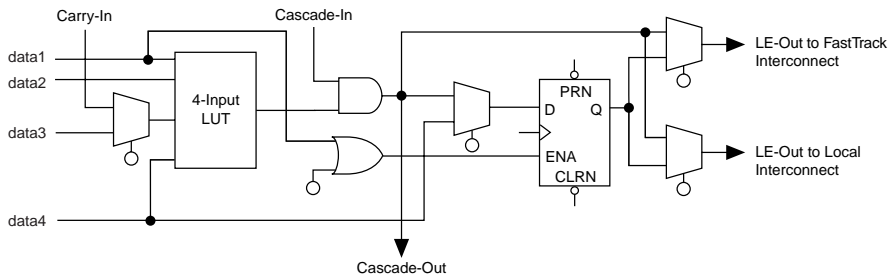
The programmable flipflop in the LE can be configured for D, T, JK, or SR operation. The clock, clear, and preset control signals on the flipflop can be driven by global signals, general-purpose I/O pins, or any internal logic. For combinational functions, the flipflop is bypassed and the LUT's output drives the LE's output.

The LE has two outputs that drive the interconnect: one drives the local interconnect, and the other drives either the row or column FastTrack Interconnect routing structure. The two outputs can be controlled independently. For example, the LUT can drive one output while the register drives the other output. This feature, called register packing, can improve LE utilization because the register and the LUT can be used for unrelated functions.

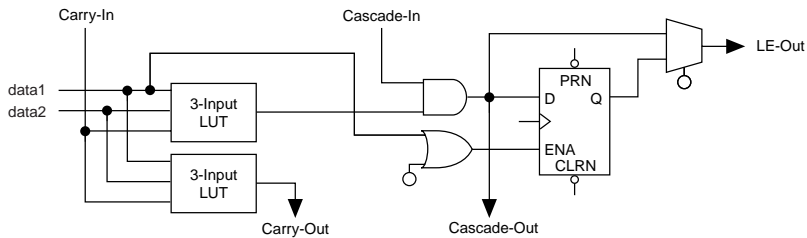
The ACEX 1K architecture provides two types of dedicated high-speed data paths that connect adjacent LEs without using local interconnect paths: carry chains and cascade chains. The carry chain supports high-speed counters and adders, and the cascade chain implements wide-input functions with minimum delay. Carry and cascade chains connect all LEs in a LAB and all LABs in the same row. Intensive use of carry and cascade chains can reduce routing flexibility. Therefore, the use of these chains should be limited to speed-critical portions of a design.

Figure 11. ACEX 1K LE Operating Modes

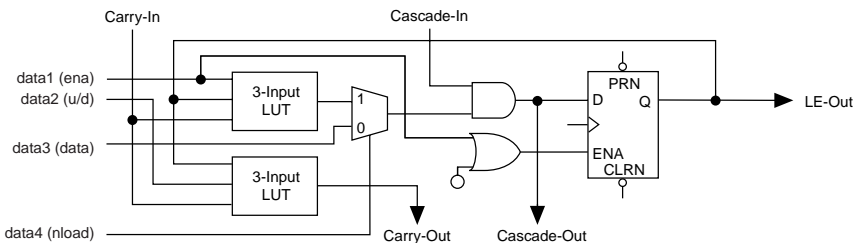
Normal Mode



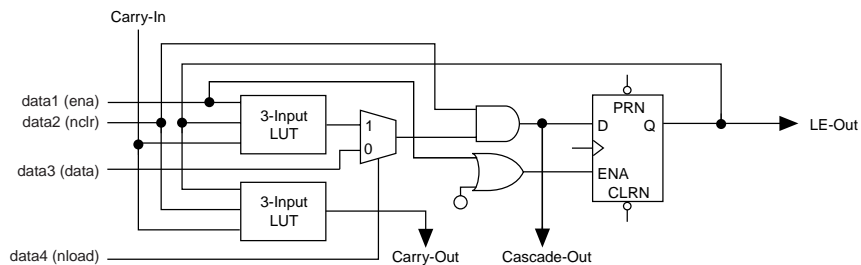
Arithmetic Mode



Up/Down Counter Mode



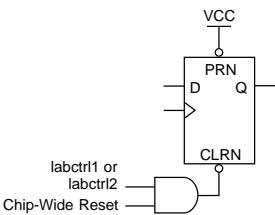
Clearable Counter Mode



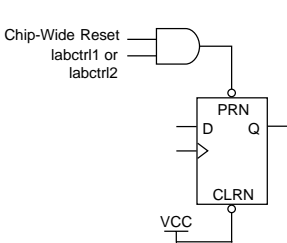
In addition to the six clear and preset modes, ACEX 1K devices provide a chip-wide reset pin that can reset all registers in the device. Use of this feature is set during design entry. In any of the clear and preset modes, the chip-wide reset overrides all other signals. Registers with asynchronous presets may be preset when the chip-wide reset is asserted. Inversion can be used to implement the asynchronous preset. Figure 12 shows examples of how to setup the preset and clear inputs for the desired functionality.

Figure 12. ACEX 1K LE Clear & Preset Modes

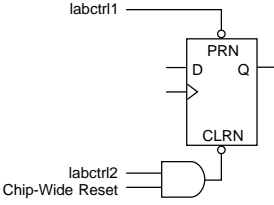
Asynchronous Clear



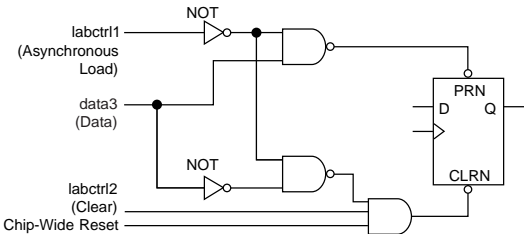
Asynchronous Preset



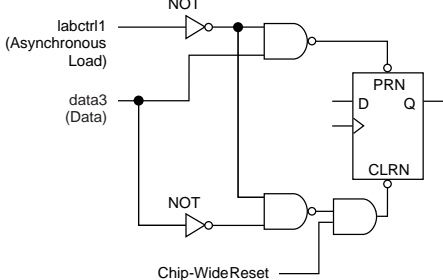
Asynchronous Preset & Clear



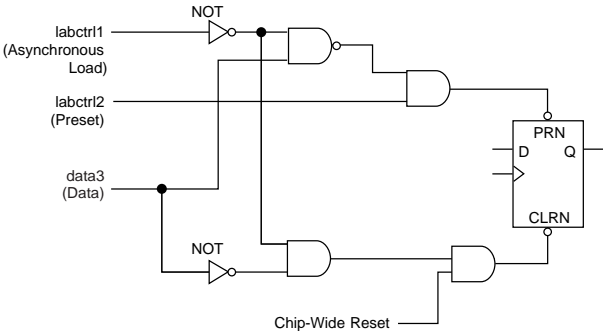
Asynchronous Load with Clear



Asynchronous Load without Clear or Preset



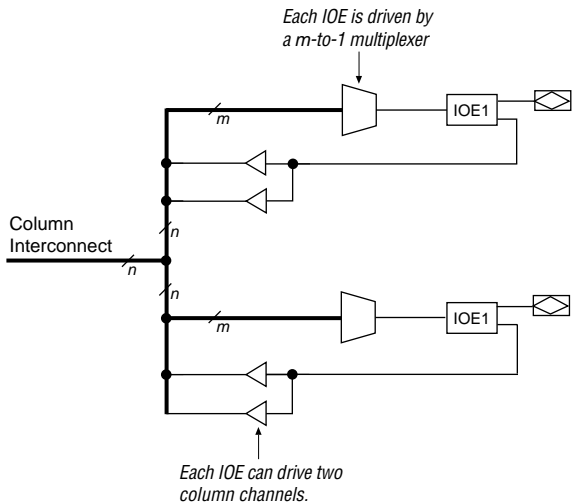
Asynchronous Load with Preset



Column-to-IOE Connections

When an IOE is used as an input, it can drive up to two separate column channels. When an IOE is used as an output, the signal is driven by a multiplexer that selects a signal from the column channels. Two IOEs connect to each side of the column channels. Each IOE can be driven by column channels via a multiplexer. The set of column channels is different for each IOE (see [Figure 17](#)).

Figure 17. ACEX 1K Column-to-IOE Connections Note (1)



Note:

(1) The values for m and n are shown in [Table 9](#).

[Table 9](#) lists the ACEX 1K column-to-IOE interconnect resources.

Table 9. ACEX 1K Column-to-IOE Interconnect Resources		
Device	Channels per Column (n)	Column Channels per Pin (m)
EP1K10	24	16
EP1K30	24	16
EP1K50	24	16
EP1K100	24	16



For more information, search for “SameFrame” in MAX+PLUS II Help.

Table 10. ACEX 1K SameFrame Pin-Out Support

Device	256-Pin FineLine BGA	484-Pin FineLine BGA
EP1K10	✓	(1)
EP1K30	✓	(1)
EP1K50	✓	✓
EP1K100	✓	✓

Note:

- (1) This option is supported with a 256-pin FineLine BGA package and SameFrame migration.

ClockLock & ClockBoost Features

To support high-speed designs, -1 and -2 speed grade ACEX 1K devices offer ClockLock and ClockBoost circuitry containing a phase-locked loop (PLL) that is used to increase design speed and reduce resource usage. The ClockLock circuitry uses a synchronizing PLL that reduces the clock delay and skew within a device. This reduction minimizes clock-to-output and setup times while maintaining zero hold times. The ClockBoost circuitry, which provides a clock multiplier, allows the designer to enhance device area efficiency by sharing resources within the device. The ClockBoost feature allows the designer to distribute a low-speed clock and multiply that clock on-device. Combined, the ClockLock and ClockBoost features provide significant improvements in system performance and bandwidth.

The ClockLock and ClockBoost features in ACEX 1K devices are enabled through the Altera software. External devices are not required to use these features. The output of the ClockLock and ClockBoost circuits is not available at any of the device pins.

The ClockLock and ClockBoost circuitry lock onto the rising edge of the incoming clock. The circuit output can drive the clock inputs of registers only; the generated clock cannot be gated or inverted.

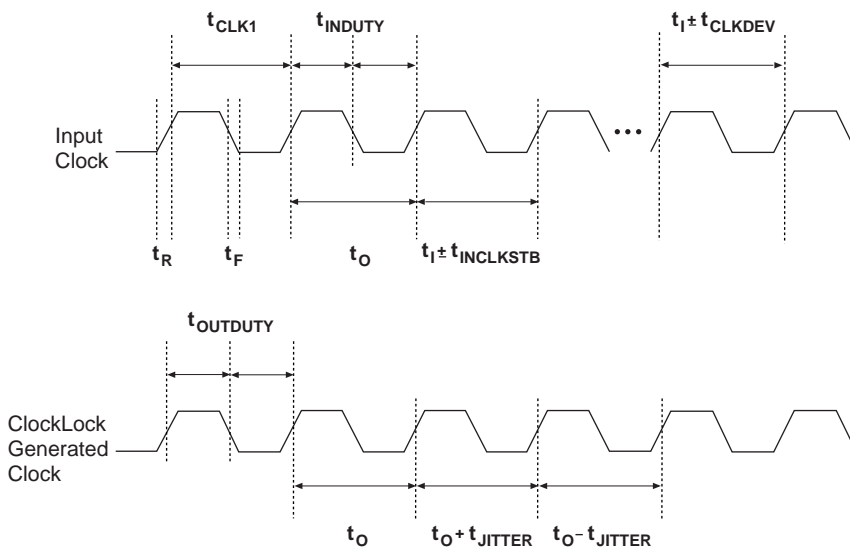
The dedicated clock pin (GCLK1) supplies the clock to the ClockLock and ClockBoost circuitry. When the dedicated clock pin is driving the ClockLock or ClockBoost circuitry, it cannot drive elsewhere in the device.

For designs that require both a multiplied and non-multiplied clock, the clock trace on the board can be connected to the GCLK1 pin. In the Altera software, the GCLK1 pin can feed both the ClockLock and ClockBoost circuitry in the ACEX 1K device. However, when both circuits are used, the other clock pin cannot be used.

ClockLock & ClockBoost Timing Parameters

For the ClockLock and ClockBoost circuitry to function properly, the incoming clock must meet certain requirements. If these specifications are not met, the circuitry may not lock onto the incoming clock, which generates an erroneous clock within the device. The clock generated by the ClockLock and ClockBoost circuitry must also meet certain specifications. If the incoming clock meets these requirements during configuration, the ClockLock and ClockBoost circuitry will lock onto the clock during configuration. The circuit will be ready for use immediately after configuration. Figure 19 shows the incoming and generated clock specifications.

Figure 19. Specifications for the Incoming & Generated Clocks *Note (1)*



Note:

- (1) The t_I parameter refers to the nominal input clock period; the t_O parameter refers to the nominal output clock period.

Table 12. ClockLock & ClockBoost Parameters for -2 Speed-Grade Devices

Symbol	Parameter	Condition	Min	Typ	Max	Unit
t_R	Input rise time				5	ns
t_F	Input fall time				5	ns
t_{INDUTY}	Input duty cycle		40		60	%
f_{CLK1}	Input clock frequency (ClockBoost clock multiplication factor equals 1)		25		80	MHz
f_{CLK2}	Input clock frequency (ClockBoost clock multiplication factor equals 2)		16		40	MHz
f_{CLKDEV}	Input deviation from user specification in the software (1)				25,000	PPM
$t_{INCLKSTB}$	Input clock stability (measured between adjacent clocks)				100	ps
t_{LOCK}	Time required for ClockLock or ClockBoost to acquire lock (3)				10	μs
t_{JITTER}	Jitter on ClockLock or ClockBoost-generated clock (4)	$t_{INCLKSTB} < 100$			250 (4)	ps
		$t_{INCLKSTB} < 50$			200 (4)	ps
$t_{OUTDUTY}$	Duty cycle for ClockLock or ClockBoost-generated clock		40	50	60	%

Notes to tables:

- (1) To implement the ClockLock and ClockBoost circuitry with the Altera software, designers must specify the input frequency. The Altera software tunes the PLL in the ClockLock and ClockBoost circuitry to this frequency. The f_{CLKDEV} parameter specifies how much the incoming clock can differ from the specified frequency during device operation. Simulation does not reflect this parameter.
- (2) Twenty-five thousand parts per million (PPM) equates to 2.5% of input clock period.
- (3) During device configuration, the ClockLock and ClockBoost circuitry is configured before the rest of the device. If the incoming clock is supplied during configuration, the ClockLock and ClockBoost circuitry locks during configuration because the t_{LOCK} value is less than the time required for configuration.
- (4) The t_{JITTER} specification is measured under long-term observation. The maximum value for t_{JITTER} is 200 ps if $t_{INCLKSTB}$ is lower than 50 ps.

I/O Configuration

This section discusses the PCI pull-up clamping diode option, slew-rate control, open-drain output option, and MultiVolt I/O interface for ACEX 1K devices. The PCI pull-up clamping diode, slew-rate control, and open-drain output options are controlled pin-by-pin via Altera software logic options. The MultiVolt I/O interface is controlled by connecting V_{CCIO} to a different voltage than V_{CCINT} . Its effect can be simulated in the Altera software via the **Global Project Device Options** dialog box (Assign menu).

PCI Pull-Up Clamping Diode Option

ACEX 1K devices have a pull-up clamping diode on every I/O, dedicated input, and dedicated clock pin. PCI clamping diodes clamp the signal to the V_{CCIO} value and are required for 3.3-V PCI compliance. Clamping diodes can also be used to limit overshoot in other systems.

Clamping diodes are controlled on a pin-by-pin basis. When V_{CCIO} is 3.3 V, a pin that has the clamping diode option turned on can be driven by a 2.5-V or 3.3-V signal, but not a 5.0-V signal. When V_{CCIO} is 2.5 V, a pin that has the clamping diode option turned on can be driven by a 2.5-V signal, but not a 3.3-V or 5.0-V signal. Additionally, a clamping diode can be activated for a subset of pins, which allows a device to bridge between a 3.3-V PCI bus and a 5.0-V device.

Slew-Rate Control

The output buffer in each IOE has an adjustable output slew rate that can be configured for low-noise or high-speed performance. A slower slew rate reduces system noise and adds a maximum delay of 4.3 ns. The fast slew rate should be used for speed-critical outputs in systems that are adequately protected against noise. Designers can specify the slew rate pin-by-pin or assign a default slew rate to all pins on a device-wide basis. The slow slew rate setting affects only the falling edge of the output.

Open-Drain Output Option

ACEX 1K devices provide an optional open-drain output (electrically equivalent to open-collector output) for each I/O pin. This open-drain output enables the device to provide system-level control signals (e.g., interrupt and write enable signals) that can be asserted by any of several devices. It can also provide an additional wired-OR plane.

MultiVolt I/O Interface

The ACEX 1K device architecture supports the MultiVolt I/O interface feature, which allows ACEX 1K devices in all packages to interface with systems of differing supply voltages. These devices have one set of V_{CC} pins for internal operation and input buffers (V_{CCINT}), and another set for I/O output drivers (V_{CCIO}).

Table 26. Interconnect Timing Microparameters *Note (1)*

Symbol	Parameter	Conditions
$t_{DIN2IOE}$	Delay from dedicated input pin to IOE control input	(7)
t_{DIN2LE}	Delay from dedicated input pin to LE or EAB control input	(7)
$t_{DIN2DATA}$	Delay from dedicated input or clock to LE or EAB data	(7)
$t_{DCLK2IOE}$	Delay from dedicated clock pin to IOE clock	(7)
$t_{DCLK2LE}$	Delay from dedicated clock pin to LE or EAB clock	(7)
$t_{SAMELAB}$	Routing delay for an LE driving another LE in the same LAB	(7)
$t_{SAMEROW}$	Routing delay for a row IOE, LE, or EAB driving a row IOE, LE, or EAB in the same row	(7)
$t_{SAMECOLUMN}$	Routing delay for an LE driving an IOE in the same column	(7)
$t_{DIFFROW}$	Routing delay for a column IOE, LE, or EAB driving an LE or EAB in a different row	(7)
$t_{TROWROWS}$	Routing delay for a row IOE or EAB driving an LE or EAB in a different row	(7)
$t_{LEPERIPH}$	Routing delay for an LE driving a control signal of an IOE via the peripheral control bus	(7)
$t_{LABCARRY}$	Routing delay for the carry-out signal of an LE driving the carry-in signal of a different LE in a different LAB	
$t_{LABCASC}$	Routing delay for the cascade-out signal of an LE driving the cascade-in signal of a different LE in a different LAB	

Notes to tables:

- (1) Microparameters are timing delays contributed by individual architectural elements. These parameters cannot be measured explicitly.
- (2) Operating conditions: $V_{CCIO} = 3.3 \text{ V} \pm 10\%$ for commercial or industrial and extended use in ACEX 1K devices
- (3) Operating conditions: $V_{CCIO} = 2.5 \text{ V} \pm 5\%$ for commercial or industrial and extended use in ACEX 1K devices.
- (4) Operating conditions: $V_{CCIO} = 2.5 \text{ V}$ or 3.3 V .
- (5) Because the RAM in the EAB is self-timed, this parameter can be ignored when the WE signal is registered.
- (6) EAB macroparameters are internal parameters that can simplify predicting the behavior of an EAB at its boundary; these parameters are calculated by summing selected microparameters.
- (7) These parameters are worst-case values for typical applications. Post-compilation timing simulation and timing analysis are required to determine actual worst-case performance.

Tables 30 through 36 show EP1K10 device internal and external timing parameters.

Table 30. EP1K10 Device LE Timing Microparameters *Note (1)*

Symbol	Speed Grade						Unit
	-1		-2		-3		
	Min	Max	Min	Max	Min	Max	
t_{LUT}		0.7		0.8		1.1	ns
t_{CLUT}		0.5		0.6		0.8	ns
t_{RLUT}		0.6		0.7		1.0	ns
t_{PACKED}		0.4		0.4		0.5	ns
t_{EN}		0.9		1.0		1.3	ns
t_{CICO}		0.1		0.1		0.2	ns
t_{CGEN}		0.4		0.5		0.7	ns
t_{CGENR}		0.1		0.1		0.2	ns
t_{CASC}		0.7		0.9		1.1	ns
t_C		1.1		1.3		1.7	ns
t_{CO}		0.5		0.7		0.9	ns
t_{COMB}		0.4		0.5		0.7	ns
t_{SU}	0.7		0.8		1.0		ns
t_H	0.9		1.0		1.1		ns
t_{PRE}		0.8		1.0		1.4	ns
t_{CLR}		0.9		1.0		1.4	ns
t_{CH}	2.0		2.5		2.5		ns
t_{CL}	2.0		2.5		2.5		ns

Table 31. EP1K10 Device IOE Timing Microparameters *Note (1)*

Symbol	Speed Grade						Unit
	-1		-2		-3		
	Min	Max	Min	Max	Min	Max	
t_{IOD}		2.6		3.1		4.0	ns
t_{IOC}		0.3		0.4		0.5	ns
t_{IOCO}		0.9		1.0		1.4	ns
t_{IOCOMB}		0.0		0.0		0.0	ns
t_{IOSU}	1.3		1.5		2.0		ns
t_{IOH}	0.9		1.0		1.4		ns
t_{IOCLR}		1.1		1.3		1.7	ns
t_{OD1}		3.1		3.7		4.1	ns
t_{OD2}		2.6		3.3		3.9	ns
t_{OD3}		5.8		6.9		8.3	ns
t_{XZ}		3.8		4.5		5.9	ns
t_{ZX1}		3.8		4.5		5.9	ns
t_{ZX2}		3.3		4.1		5.7	ns
t_{ZX3}		6.5		7.7		10.1	ns
t_{INREG}		3.7		4.3		5.7	ns
t_{IOFD}		0.9		1.0		1.4	ns
t_{INCOMB}		1.9		2.3		3.0	ns

Table 32. EP1K10 Device EAB Internal Microparameters *Note (1)*

Symbol	Speed Grade						Unit
	-1		-2		-3		
	Min	Max	Min	Max	Min	Max	
$t_{EABDATA1}$		1.8		1.9		1.9	ns
$t_{EABDATA2}$		0.6		0.7		0.7	ns
t_{EABWE1}		1.2		1.2		1.2	ns
t_{EABWE2}		0.4		0.4		0.4	ns
t_{EABRE1}		0.9		0.9		0.9	ns
t_{EABRE2}		0.4		0.4		0.4	ns
t_{EABCLK}		0.0		0.0		0.0	ns
t_{EABCO}		0.3		0.3		0.3	ns
$t_{EABYPASS}$		0.5		0.6		0.6	ns
t_{EABSU}	1.0		1.0		1.0		ns
t_{EABH}	0.5		0.4		0.4		ns
t_{EABCLR}	0.3		0.3		0.3		ns
t_{AA}		3.4		3.6		3.6	ns
t_{WP}	2.7		2.8		2.8		ns
t_{RP}	1.0		1.0		1.0		ns
t_{WDSU}	1.0		1.0		1.0		ns
t_{WDH}	0.1		0.1		0.1		ns
t_{WASU}	1.8		1.9		1.9		ns
t_{WAH}	1.9		2.0		2.0		ns
t_{RASU}	3.1		3.5		3.5		ns
t_{RAH}	0.2		0.2		0.2		ns
t_{WO}		2.7		2.8		2.8	ns
t_{DD}		2.7		2.8		2.8	ns
t_{EABOUT}		0.5		0.6		0.6	ns
t_{EABCH}	1.5		2.0		2.0		ns
t_{EABCL}	2.7		2.8		2.8		ns

Table 36. EP1K10 External Bidirectional Timing Parameters *Notes (1), (3)*

Symbol	Speed Grade						Unit
	-1		-2		-3		
	Min	Max	Min	Max	Min	Max	
t _{INSUBIDIR} (2)	2.2		2.3		3.2		ns
t _{INHBIDIR} (2)	0.0		0.0		0.0		ns
t _{OUTCOBIDIR} (2)	2.0	6.6	2.0	7.8	2.0	9.6	ns
t _{XZBIDIR} (2)		8.8		11.2		14.0	ns
t _{ZXBIDIR} (2)		8.8		11.2		14.0	ns
t _{INSUBIDIR} (4)	3.1		3.3		–	–	
t _{INHBIDIR} (4)	0.0		0.0		–		
t _{OUTCOBIDIR} (4)	0.5	5.1	0.5	6.4	–	–	ns
t _{XZBIDIR} (4)		7.3		9.2		–	ns
t _{ZXBIDIR} (4)		7.3		9.2		–	ns

Notes to tables:

- (1) All timing parameters are described in Tables 22 through 29 in this data sheet.
 (2) This parameter is measured without the use of the ClockLock or ClockBoost circuits.
 (3) These parameters are specified by characterization.
 (4) This parameter is measured with the use of the ClockLock or ClockBoost circuits.

Tables 37 through 43 show EP1K30 device internal and external timing parameters.

Table 37. EP1K30 Device LE Timing Microparameters (Part 1 of 2) *Note (1)*

Symbol	Speed Grade						Unit
	-1		-2		-3		
	Min	Max	Min	Max	Min	Max	
t_{LUT}		0.7		0.8		1.1	ns
t_{CLUT}		0.5		0.6		0.8	ns
t_{RLUT}		0.6		0.7		1.0	ns
t_{PACKED}		0.3		0.4		0.5	ns
t_{EN}		0.6		0.8		1.0	ns
t_{CICO}		0.1		0.1		0.2	ns
t_{CGEN}		0.4		0.5		0.7	ns
t_{CGENR}		0.1		0.1		0.2	ns
t_{CASC}		0.6		0.8		1.0	ns
t_C		0.0		0.0		0.0	ns
t_{CO}		0.3		0.4		0.5	ns

Table 39. EP1K30 Device EAB Internal Microparameters *Note (1)*

Symbol	Speed Grade						Unit
	-1		-2		-3		
	Min	Max	Min	Max	Min	Max	
$t_{EABDATA1}$		1.7		2.0		2.3	ns
$t_{EABDATA1}$		0.6		0.7		0.8	ns
t_{EABWE1}		1.1		1.3		1.4	ns
t_{EABWE2}		0.4		0.4		0.5	ns
t_{EABRE1}		0.8		0.9		1.0	ns
t_{EABRE2}		0.4		0.4		0.5	ns
t_{EABCLK}		0.0		0.0		0.0	ns
t_{EABCO}		0.3		0.3		0.4	ns
$t_{EABYPASS}$		0.5		0.6		0.7	ns
t_{EABSU}	0.9		1.0		1.2		ns
t_{EABH}	0.4		0.4		0.5		ns
t_{EABCLR}	0.3		0.3		0.3		ns
t_{AA}		3.2		3.8		4.4	ns
t_{WP}	2.5		2.9		3.3		ns
t_{RP}	0.9		1.1		1.2		ns
t_{WDSU}	0.9		1.0		1.1		ns
t_{WDH}	0.1		0.1		0.1		ns
t_{WASU}	1.7		2.0		2.3		ns
t_{WAH}	1.8		2.1		2.4		ns
t_{RASU}	3.1		3.7		4.2		ns
t_{RAH}	0.2		0.2		0.2		ns
t_{WO}		2.5		2.9		3.3	ns
t_{DD}		2.5		2.9		3.3	ns
t_{EABOUT}		0.5		0.6		0.7	ns
t_{EABCH}	1.5		2.0		2.3		ns
t_{EABCL}	2.5		2.9		3.3		ns

Table 41. EP1K30 Device Interconnect Timing Microparameters *Note (1)*

Symbol	Speed Grade						Unit
	-1		-2		-3		
	Min	Max	Min	Max	Min	Max	
$t_{DIN2IOE}$		1.8		2.4		2.9	ns
t_{DIN2LE}		1.5		1.8		2.4	ns
$t_{DIN2DATA}$		1.5		1.8		2.2	ns
$t_{DCLK2IOE}$		2.2		2.6		3.0	ns
$t_{DCLK2LE}$		1.5		1.8		2.4	ns
$t_{SAMELAB}$		0.1		0.2		0.3	ns
$t_{SAMEROW}$		2.0		2.4		2.7	ns
$t_{SAMECOLUMN}$		0.7		1.0		0.8	ns
$t_{DIFFROW}$		2.7		3.4		3.5	ns
$t_{TWOROWS}$		4.7		5.8		6.2	ns
$t_{LEPERIPH}$		2.7		3.4		3.8	ns
$t_{LABCARRY}$		0.3		0.4		0.5	ns
$t_{LABCASC}$		0.8		0.8		1.1	ns

Table 42. EP1K30 External Timing Parameters *Notes (1), (2)*

Symbol	Speed Grade						Unit
	-1		-2		-3		
	Min	Max	Min	Max	Min	Max	
t _{DDR}		8.0		9.5		12.5	ns
t _{INSU} (3)	2.1		2.5		3.9		ns
t _{INH} (3)	0.0		0.0		0.0		ns
t _{OUTCO} (3)	2.0	4.9	2.0	5.9	2.0	7.6	ns
t _{INSU} (4)	1.1		1.5		–		ns
t _{INH} (4)	0.0		0.0		–		ns
t _{OUTCO} (4)	0.5	3.9	0.5	4.9	–	–	ns
t _{PCISU}	3.0		4.2		–		ns
t _{PCIH}	0.0		0.0		–		ns
t _{PCICO}	2.0	6.0	2.0	7.5	–	–	ns

Table 43. EP1K30 External Bidirectional Timing Parameters *Notes (1), (2)*

Symbol	Speed Grade						Unit
	-1		-2		-3		
	Min	Max	Min	Max	Min	Max	
t _{INSUBIDIR} (3)	2.8		3.9		5.2		ns
t _{INHBIDIR} (3)	0.0		0.0		0.0		ns
t _{INSUBIDIR} (4)	3.8		4.9		–		ns
t _{INHBIDIR} (4)	0.0		0.0		–		ns
t _{OUTCOBIDIR} (3)	2.0	4.9	2.0	5.9	2.0	7.6	ns
t _{XZBIDIR} (3)		6.1		7.5		9.7	ns
t _{ZXBIDIR} (3)		6.1		7.5		9.7	ns
t _{OUTCOBIDIR} (4)	0.5	3.9	0.5	4.9	–	–	ns
t _{XZBIDIR} (4)		5.1		6.5		–	ns
t _{ZXBIDIR} (4)		5.1		6.5		–	ns

Notes to tables:

- (1) All timing parameters are described in Tables 22 through 29 in this data sheet.
- (2) These parameters are specified by characterization.
- (3) This parameter is measured without the use of the ClockLock or ClockBoost circuits.
- (4) This parameter is measured with the use of the ClockLock or ClockBoost circuits.

Tables 44 through 50 show EP1K50 device external timing parameters.

Table 44. EP1K50 Device LE Timing Microparameters (Part 1 of 2) *Note (1)*

Symbol	Speed Grade						Unit
	-1		-2		-3		
	Min	Max	Min	Max	Min	Max	
t_{LUT}		0.6		0.8		1.1	ns
t_{CLUT}		0.5		0.6		0.8	ns
t_{RLUT}		0.6		0.7		0.9	ns
t_{PACKED}		0.2		0.3		0.4	ns
t_{EN}		0.6		0.7		0.9	ns
t_{CICO}		0.1		0.1		0.1	ns
t_{CGEN}		0.4		0.5		0.6	ns
t_{CGENR}		0.1		0.1		0.1	ns
t_{CASC}		0.5		0.8		1.0	ns
t_C		0.5		0.6		0.8	ns

Table 48. EP1K50 Device Interconnect Timing Microparameters *Note (1)*

Symbol	Speed Grade						Unit
	-1		-2		-3		
	Min	Max	Min	Max	Min	Max	
$t_{DIN2IOE}$		3.1		3.7		4.6	ns
t_{DIN2LE}		1.7		2.1		2.7	ns
$t_{DIN2DATA}$		2.7		3.1		5.1	ns
$t_{DCLK2IOE}$		1.6		1.9		2.6	ns
$t_{DCLK2LE}$		1.7		2.1		2.7	ns
$t_{SAMELAB}$		0.1		0.1		0.2	ns
$t_{SAMEROW}$		1.5		1.7		2.4	ns
$t_{SAMECOLUMN}$		1.0		1.3		2.1	ns
$t_{DIFFROW}$		2.5		3.0		4.5	ns
$t_{TROWROWS}$		4.0		4.7		6.9	ns
$t_{LEPERIPH}$		2.6		2.9		3.4	ns
$t_{LABCARRY}$		0.1		0.2		0.2	ns
$t_{LABCASC}$		0.8		1.0		1.3	ns

Table 49. EP1K50 External Timing Parameters *Note (1)*

Symbol	Speed Grade						Unit
	-1		-2		-3		
	Min	Max	Min	Max	Min	Max	
t _{DDR}		8.0		9.5		12.5	ns
t _{INSU} (2)	2.4		2.9		3.9		ns
t _{INH} (2)	0.0		0.0		0.0		ns
t _{OUTCO} (2)	2.0	4.3	2.0	5.2	2.0	7.3	ns
t _{INSU} (3)	2.4		2.9		–		ns
t _{INH} (3)	0.0		0.0		–		ns
t _{OUTCO} (3)	0.5	3.3	0.5	4.1	–	–	ns
t _{PCISU}	2.4		2.9		–		ns
t _{PCIH}	0.0		0.0		–		ns
t _{PCICO}	2.0	6.0	2.0	7.7	–	–	ns

The $I_{CCACTIVE}$ value can be calculated with the following equation:

$$I_{CCACTIVE} = K \times f_{MAX} \times N \times \text{tog}_{LC} \text{ (}\mu\text{A)}$$

Where:

- f_{MAX} = Maximum operating frequency in MHz
- N = Total number of LEs used in the device
- tog_{LC} = Average percent of LEs toggling at each clock (typically 12.5%)
- K = Constant

Table 58 provides the constant (K) values for ACEX 1K devices.

Table 58. ACEX 1K Constant Values	
Device	K Value
EP1K10	4.5
EP1K30	4.5
EP1K50	4.5
EP1K100	4.5

This supply power calculation provides an I_{CC} estimate based on typical conditions with no output load. The actual I_{CC} should be verified during operation because this measurement is sensitive to the actual pattern in the device and the environmental operating conditions.

To better reflect actual designs, the power model (and the constant K in the power calculation equations) for continuous interconnect ACEX 1K devices assumes that LEs drive FastTrack Interconnect channels. In contrast, the power model of segmented FPGAs assumes that all LEs drive only one short interconnect segment. This assumption may lead to inaccurate results when compared to measured power consumption for actual designs in segmented FPGAs.

Figure 31 shows the relationship between the current and operating frequency of ACEX 1K devices. For information on other ACEX 1K devices, contact Altera Applications at (800) 800-EPLD.